

綠固科技股份有限公司

Greencure Technology Corporation



加熱硬化型可剝離耐焊油墨(LM-600 PSM-200B)

THERMAL-CURING PEELABLE SOLDER MASK

LM-600 PSM-200B 系列為加熱硬化型可剝離的耐焊油墨，具有快速硬化及良好的印刷性，乾燥後其耐熱性及可剝離性極優因此可以用於FPCB製程中金手指的焊錫保護，使用後可完全剝除無任何殘膠(SCUM)而且耐化學品特佳，因此也可以進行抗電鍍製程。

LM-600 PSM-200B series is temporary solder mask ink designed for using in Flexible printed circuit fabrication for gold finger. It has fast curing speed, excellent printing properties and forming a tough protective film after thermal curing. The cured film will withstand solder heat, keeping excellent electrical, peelable properties, and chemicals resistance for gold plating.

技術資料 Technical Data

項目	PSM-200B
顏色 Color	藍色 BLUE
黏度 Viscosity(25°C)	900 ± 100 PS (VT-04, #2 針, #2 Spindle)
耐焊錫性 Resistance to molten solder	280±5 °C ,3 秒, ≥2 次 280±5 °C , 3 seconds, ≥2 times
貯存安定性 Shelf life at 20-30 °C under dark packing	10 個月 month

使用條件

網目 T	11-24 T
乳膠膜厚 Stencil thickness	50-100 micron
刮刀 squeegee	60-65 度鈍角 flat angle
硬化條件 Curing Condition	150±5 °C, 30MINS
稀釋 dilution	不建議使用溶劑稀釋 The addition of solvent is not recommended

以上各項數據僅供參考

The above information is for reference only.

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